



**ALPHA & OMEGA**  
SEMICONDUCTOR

**AOCA35212E**

**24V Common-Drain Dual N-Channel MOSFET**

### General Description

- Trench Power MOSFET technology
- Low  $R_{SS(ON)}$
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS 2.0 and Halogen-Free Compliant

### Applications

- Battery protection switch
- Mobile device battery charging and discharging

### Product Summary

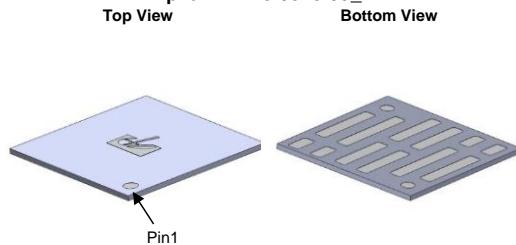
$V_{SS}$	24V
$R_{SS(ON)}$ (at $V_{GS}=10V$ )	< 2mΩ
$R_{SS(ON)}$ (at $V_{GS}=8V$ )	< 2.2mΩ
$R_{SS(ON)}$ (at $V_{GS}=4.5V$ )	< 3.5mΩ

### Typical ESD protection

HBM Class 2

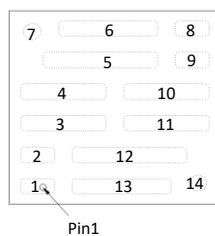


AlphaDFN™ 3.03x3.03\_14

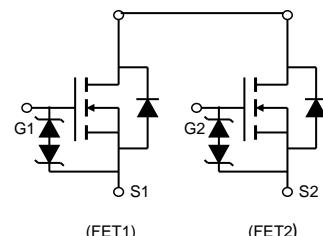


Top View      Bottom View

Top View



1,2,3,4,5,6. Source1(FET1)      7. Gate1 (FET1)  
8,9,10,11,12,13 Source2(FET2)      14. Gate2 (FET2)



### Orderable Part Number

AOCA35212E

### Package Type

AlphaDFN™3.03x3.03\_14

### Form

Tape & Reel

### Minimum Order Quantity

5000

### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	$V_{SS}$	24	V
Gate-Source Voltage	$V_{GS}$	$\pm 16$	V
Source Current(DC) <sup>Note1</sup>	$I_S$	34	A
Source Current(Pulse) <sup>Note2</sup>	$I_{SM}$	170	
Power Dissipation <sup>Note1</sup>	$P_D$	3.1	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient $t \leq 10s$	$R_{\theta JA}$	30	°C/W
Maximum Junction-to-Ambient Steady-State		40	°C/W

**Note 1.**  $I_S$  rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

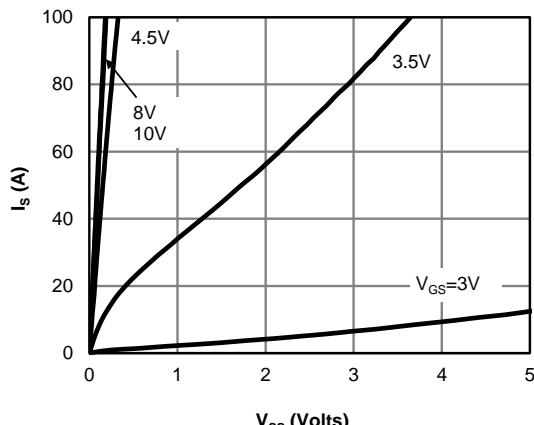
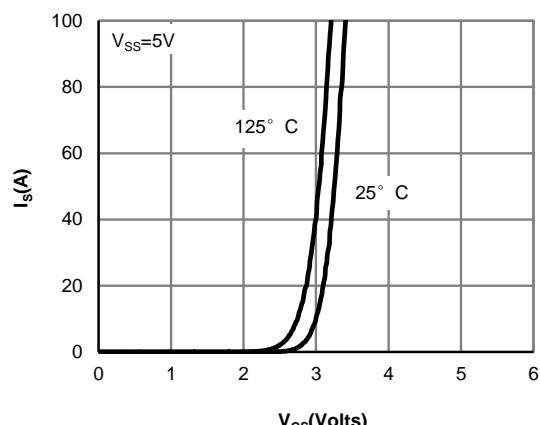
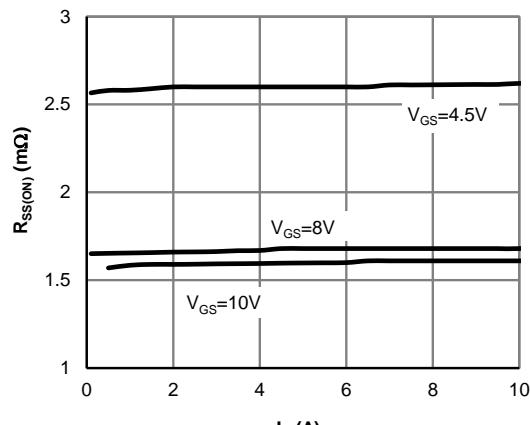
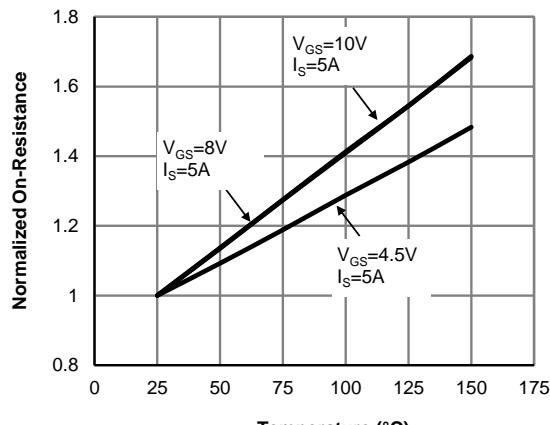
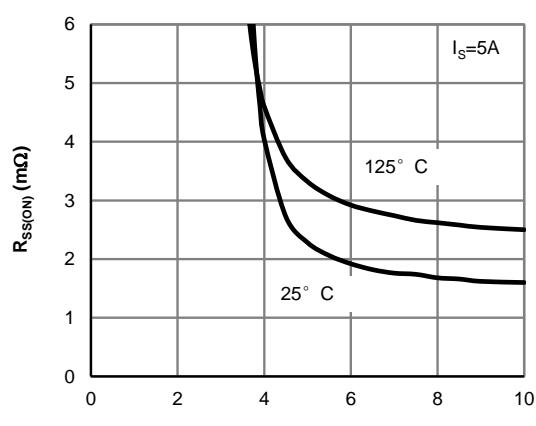
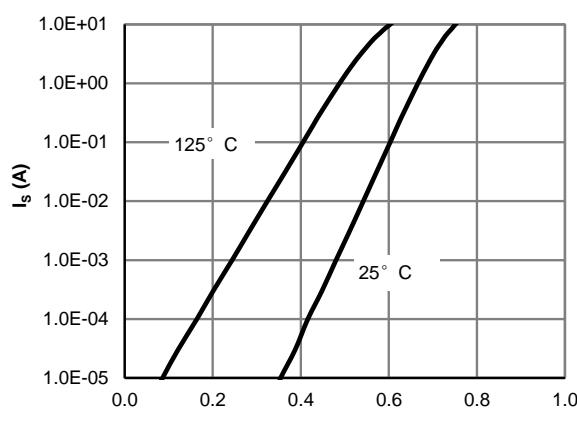
**Note 2.** PW <10  $\mu\text{s}$  pulses, duty cycle 1% max.

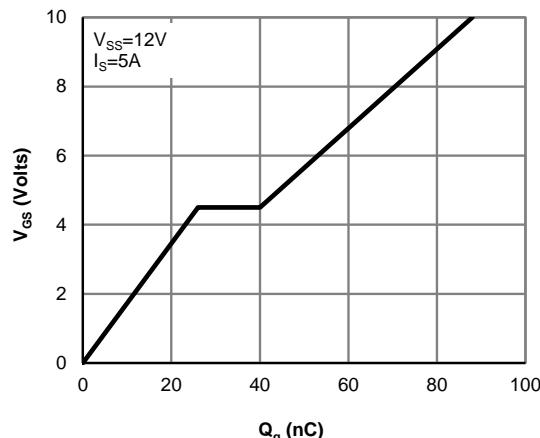
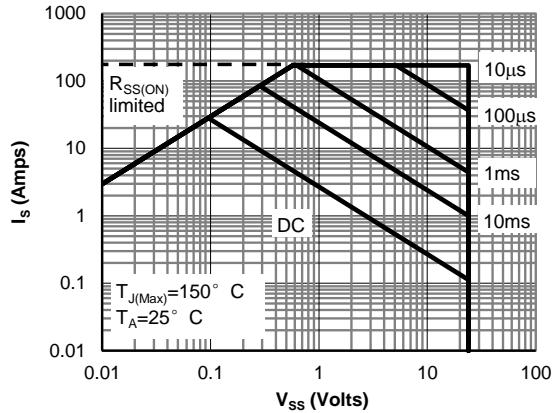
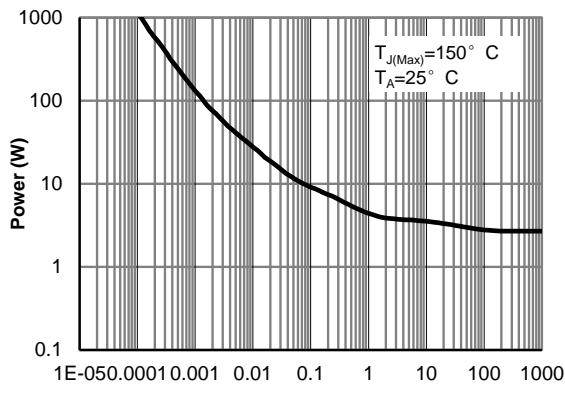
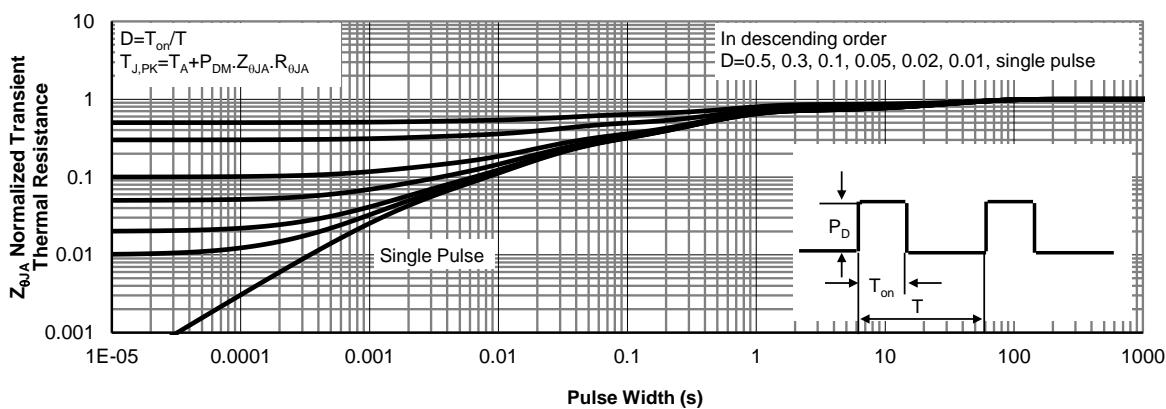
**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{SSS}}$	Source-Source Breakdown Voltage	$I_S=250\mu\text{A}, V_{GS}=0\text{V}$	Test Circuit 6	24		V
$I_{\text{SSS}}$	Zero Gate Voltage Source Current	$V_{SS}=24\text{V}, V_{GS}=0\text{V}$	Test Circuit 1 $T_J=55^\circ\text{C}$		1 5	$\mu\text{A}$
$I_{GSS}$	Gate leakage current	$V_{SS}=0\text{V}, V_{GS}=\pm16\text{V}$	Test Circuit 2		$\pm10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{SS}=V_{GS}, I_S=250\mu\text{A}$	Test Circuit 3	1.5	1.95	2.4
$R_{SS(\text{ON})}$	Static Source to Source On-Resistance	$V_{GS}=10\text{V}, I_S=5\text{A}$	Test Circuit 4 $T_J=125^\circ\text{C}$	1.1 1.7	1.6 2.5	2 3
		$V_{GS}=8\text{V}, I_S=5\text{A}$	Test Circuit 4	1.2	1.68	2.2
		$V_{GS}=4.5\text{V}, I_S=5\text{A}$	Test Circuit 4	1.8	2.6	3.5
$g_{FS}$	Forward Transconductance	$V_{SS}=5\text{V}, I_S=5\text{A}$	Test Circuit 3		40	S
$V_{FSS}$	Forward Source to Source Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	Test Circuit 5		0.65	1
<b>DYNAMIC PARAMETERS</b>						
$R_g$	Gate resistance	$f=1\text{MHz}$			1.4	$\text{k}\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{G1S1}=10\text{V}, V_{SS}=12\text{V}, I_S=5\text{A}$			88	nC
$t_{D(on)}$	Turn-On DelayTime	$V_{G1S1}=10\text{V}, V_{SS}=12\text{V}, R_L=1.2\Omega,$ $R_{\text{GEN}}=3\Omega$	Test Circuit 8		2.2	$\mu\text{s}$
$t_r$	Turn-On Rise Time				3.6	$\mu\text{s}$
$t_{D(off)}$	Turn-Off DelayTime				2.8	$\mu\text{s}$
$t_f$	Turn-Off Fall Time				8.9	$\mu\text{s}$

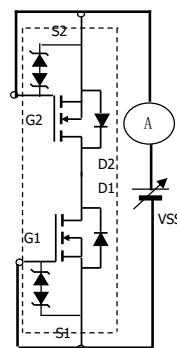
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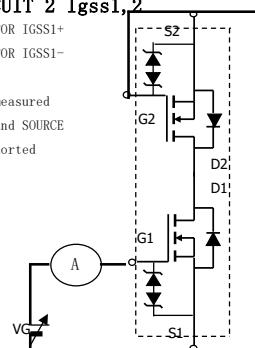
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 1: On-Region Characteristics**

**Figure 2: Transfer Characteristics**

**Figure 3: On-Resistance vs. Source Current and Gate Voltage**

**Figure 4: On-Resistance vs. Junction Temperature**

**Figure 5: On-Resistance vs. Gate-Source Voltage**

**Figure 6: Forward Source to Source Characteristics**

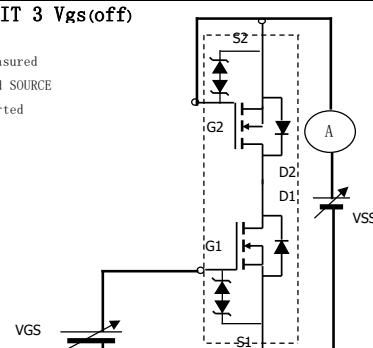
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 7: Gate-Charge Characteristics**

**Figure 8: Maximum Forward Biased Safe Operating Area (Note1)**

**Figure 9: Single Pulse Power Rating Junction-to-Ambient (Note1)**

**Figure 10: Normalized Maximum Transient Thermal Impedance (Note1)**

**TEST CIRCUIT 1 Isss**

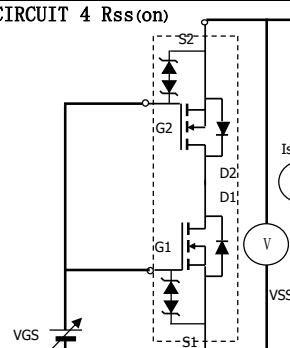
 POSITIVE VSS FOR ISSS+  
 NEGATIVE VSS FOR ISSS-

**TEST CIRCUIT 2 Igss1,2**

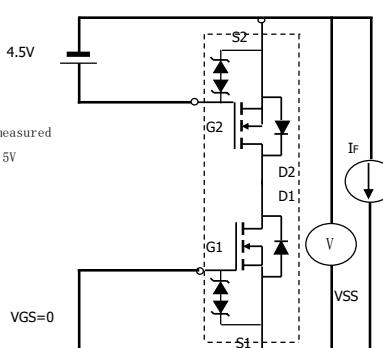
 POSITIVE VGS FOR IGSS1+  
 NEGATIVE VGS FOR IGSS1-

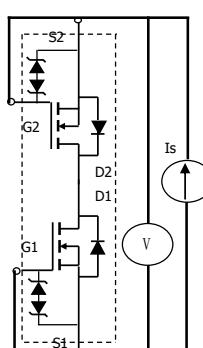
 When FET1 is measured  
 between GATE and SOURCE  
 of FET2 are shorted

**TEST CIRCUIT 3 Vgs(off)**

 When FET1 is measured  
 between GATE and SOURCE  
 of FET2 are shorted

**TEST CIRCUIT 4 Rss(on)**

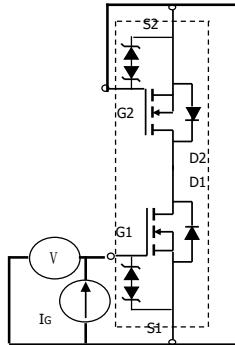
Vss/Is


**TEST CIRCUIT 5 VF(ss)1,2**

 4.5V  
 When FET1 measured  
 FET2 VGS=4.5V

**TEST CIRCUIT 6 BVdss**

 POSITIVE VSS FOR ISSS+  
 NEGATIVE VSS FOR ISSS-

**TEST CIRCUIT 7 BVgs01,2**

 POSITIVE VSS FOR ISSS+  
 NEGATIVE VSS FOR ISSS-

 When FET1 is measured  
 between GATE and SOURCE  
 of FET2 are shorted

**TEST CIRCUIT 8  
Switching time**
